

# Dual NPN General Purpose Amplifier Transistor

## EMX2DXV6T5

This NPN transistor is designed for general purpose amplifier applications. This device is housed in the SOT-563 package which is designed for low power surface mount applications, where board space is at a premium.

### Features

- Reduces Board Space
- High  $h_{FE}$ , 210–460 (Typical)
- Low  $V_{CE(sat)}$ , < 0.5 V
- These are Pb-Free Devices

### MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ )

Rating	Symbol	Value	Unit
Collector-Base Voltage	$V_{(BR)CBO}$	60	Vdc
Collector-Emitter Voltage	$V_{(BR)CEO}$	50	Vdc
Emitter-Base Voltage	$V_{(BR)EBO}$	7.0	Vdc
Collector Current – Continuous	$I_C$	100	mAdc

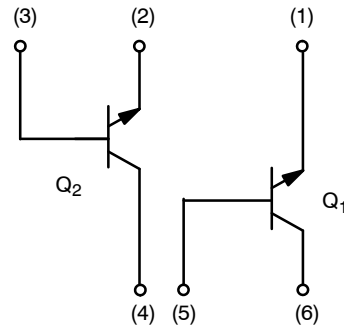
### THERMAL CHARACTERISTICS

Characteristic (One Junction Heated)	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	357 (Note 1) 2.9 (Note 1)	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	350 (Note 1)	$^\circ\text{C}/\text{W}$
Characteristic (Both Junctions Heated)	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	500 (Note 1) 4.0 (Note 1)	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	250 (Note 1)	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

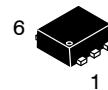
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-4 @ Minimum Pad

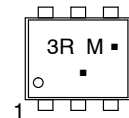
## DUAL NPN GENERAL PURPOSE AMPLIFIER TRANSISTORS SURFACE MOUNT



### MARKING DIAGRAM



SOT-563  
CASE 463A  
STYLE 2



3R = Specific Device Code

M = Month Code

▪ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
EMX2DXV6T5G	SOT-563 (Pb-Free)	8000/Tape & Reel
EMX2DXV6T1G	SOT-563 (Pb-Free)	4000/Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## EMX2DXV6T5

### ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ )

Characteristic	Symbol	Min	Typ	Max	Unit
Collector-Base Breakdown Voltage ( $I_C = 50 \mu\text{A}$ , $I_E = 0$ )	$V_{(BR)CBO}$	60	-	-	Vdc
Collector-Emitter Breakdown Voltage ( $I_C = 1.0 \text{mA}$ , $I_B = 0$ )	$V_{(BR)CEO}$	50	-	-	Vdc
Emitter-Base Breakdown Voltage ( $I_E = 50 \mu\text{A}$ , $I_C = 0$ )	$V_{(BR)EBO}$	7.0	-	-	Vdc
Collector-Base Cutoff Current ( $V_{CB} = 60 \text{Vdc}$ , $I_E = 0$ )	$I_{CBO}$	-	-	0.5	$\mu\text{A}$
Emitter-Base Cutoff Current ( $V_{EB} = 7.0 \text{Vdc}$ , $I_B = 0$ )	$I_{EBO}$	-	-	0.5	$\mu\text{A}$
Collector-Emitter Saturation Voltage (Note 2) ( $I_C = 50 \text{mA}$ , $I_B = 5.0 \text{mA}$ )	$V_{CE(sat)}$	-	-	0.4	Vdc
DC Current Gain (Note 3) ( $V_{CE} = 6.0 \text{Vdc}$ , $I_C = 1.0 \text{mA}$ )	$h_{FE}$	120	-	560	-
Transition Frequency ( $V_{CE} = 12 \text{Vdc}$ , $I_C = 2.0 \text{mA}$ , $f = 30 \text{MHz}$ )	$f_T$	-	180	-	MHz
Output Capacitance ( $V_{CB} = 12 \text{Vdc}$ , $I_C = 0 \text{A}$ , $f = 1 \text{MHz}$ )	$C_{OB}$	-	2.0	-	pF

2. Device mounted on a FR-4 glass epoxy printed circuit board using the minimum recommended footprint.

3. Pulse Test: Pulse Width  $\leq 300 \mu\text{s}$ , D.C.  $\leq 2\%$ .

# EMX2DXV6T5

## TYPICAL ELECTRICAL CHARACTERISTICS

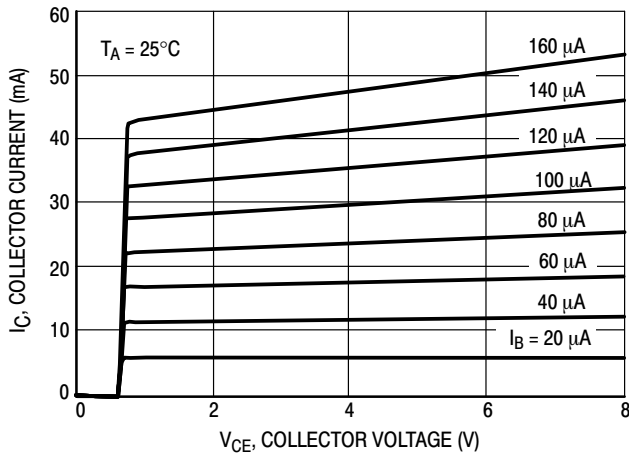


Figure 1.  $I_C - V_{CE}$

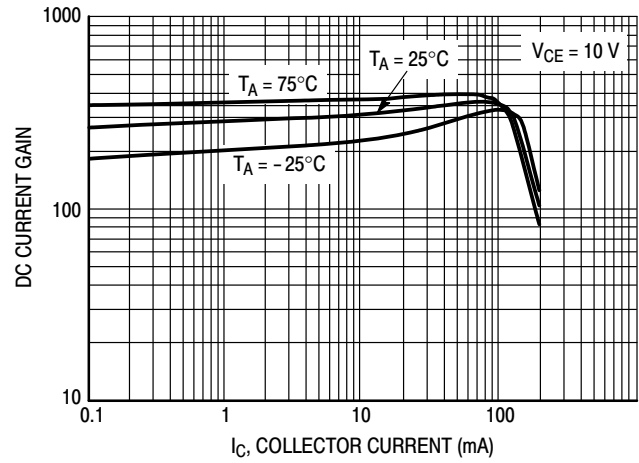


Figure 2. DC Current Gain

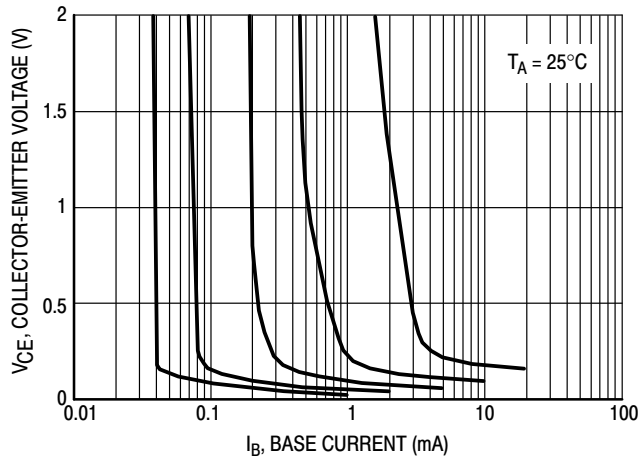


Figure 3. Collector Saturation Region

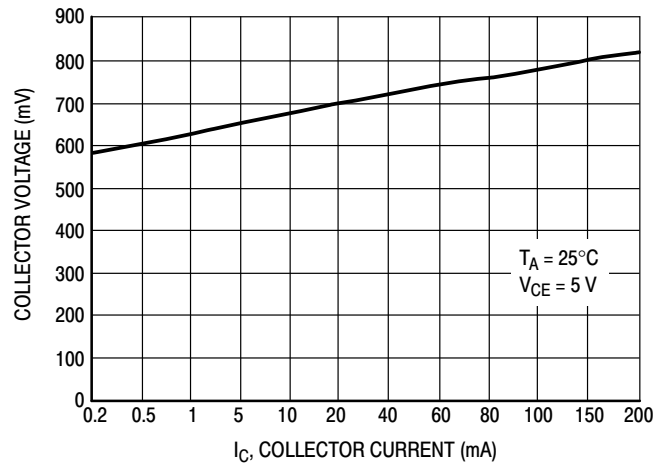


Figure 4. On Voltage

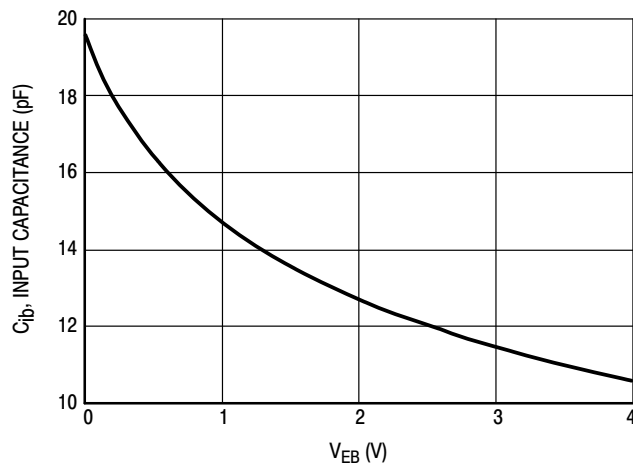


Figure 5. Capacitance

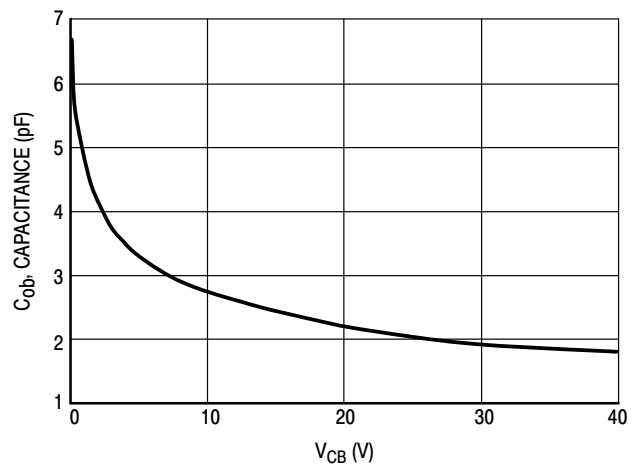


Figure 6. Capacitance

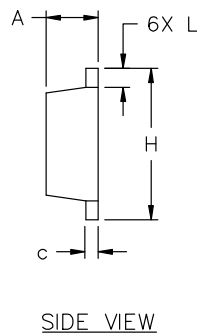
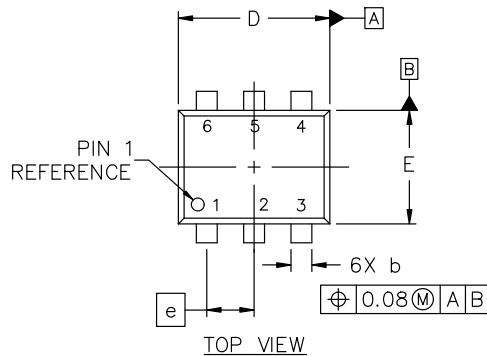


SOT-563-6 1.60x1.20x0.55, 0.50P  
CASE 463A  
ISSUE J

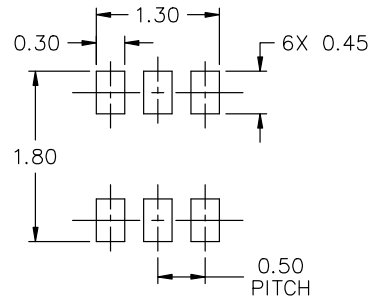
DATE 15 FEB 2024

NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSION ARE IN MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.50	0.55	0.60
b	0.17	0.22	0.27
c	0.08	0.13	0.18
D	1.50	1.60	1.70
E	1.10	1.20	1.30
e	0.50 BSC		
H	1.50	1.60	1.70
L	0.10	0.20	0.30



STYLE 1:  
PIN 1. EMITTER 1  
2. BASE 1  
3. COLLECTOR 2  
4. EMITTER 2  
5. BASE 2  
6. COLLECTOR 1

STYLE 2:  
PIN 1. EMITTER 1  
2. EMITTER 2  
3. BASE 2  
4. COLLECTOR 2  
5. BASE 1  
6. COLLECTOR 1

STYLE 3:  
PIN 1. CATHODE 1  
2. CATHODE 1  
3. ANODE/ANODE 2  
4. CATHODE 2  
5. CATHODE 2  
6. ANODE/ANODE 1

STYLE 4:  
PIN 1. COLLECTOR  
2. COLLECTOR  
3. BASE  
4. EMITTER  
5. COLLECTOR  
6. COLLECTOR

STYLE 5:  
PIN 1. CATHODE  
2. CATHODE  
3. ANODE  
4. ANODE  
5. CATHODE  
6. CATHODE

STYLE 6:  
PIN 1. CATHODE  
2. ANODE  
3. CATHODE  
4. CATHODE  
5. CATHODE  
6. CATHODE

STYLE 7:  
PIN 1. CATHODE  
2. ANODE  
3. CATHODE  
4. CATHODE  
5. ANODE  
6. CATHODE

STYLE 8:  
PIN 1. DRAIN  
2. DRAIN  
3. GATE  
4. SOURCE  
5. DRAIN  
6. DRAIN

STYLE 9:  
PIN 1. SOURCE 1  
2. GATE 1  
3. DRAIN 2  
4. SOURCE 2  
5. GATE 2  
6. DRAIN 1

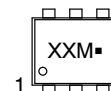
STYLE 10:  
PIN 1. CATHODE 1  
2. N/C  
3. CATHODE 2  
4. ANODE 2  
5. N/C  
6. ANODE 1

STYLE 11:  
PIN 1. EMITTER 2  
2. BASE 2  
3. COLLECTOR 1  
4. EMITTER 1  
5. BASE 1  
6. COLLECTOR 2

RECOMMENDED MOUNTING FOOTPRINT\*

\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM\*



XX = Specific Device Code  
M = Month Code  
▪ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	SOT-563-6 1.60x1.20x0.55, 0.50P	PAGE 1 OF 1

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